SAMSUNG ELECTRO-MECHANICS

RoHS+Halogen Compliant ecoparts

SPECIFICATION (Reference sheet)

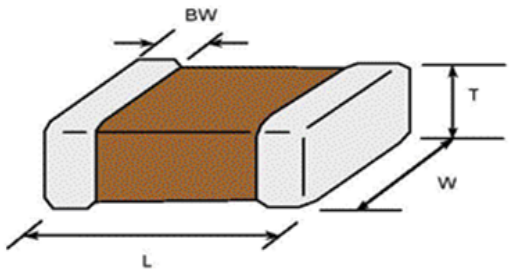
· **Supplier : Samsung electro-mechanics**
· **Product : Multi-layer Ceramic Capacitor**
· **Samsung P/N : CL31C102JHHNNNE**
· **Description : CAP, 1㎋, 630V, ± 5%, C0G, 1206**

A. Samsung Part Number

CL	31	C	102	J	H	H	N	N	N	E
①	②	③	④	⑤	⑥	⑦	⑧	⑨	⑩	⑪

①	**Series**	Samsung Multi-layer Ceramic Capacitor			
②	**Size**	1206 (inch code)	L: 3.20 ± 0.20 mm	W: 1.60 ± 0.20 mm	
③	**Dielectric**	C0G	⑧ **Inner electrode**	Ni	
④	**Capacitance**	1 ㎋	**Termination**	Cu	
⑤	**Capacitance tolerance**	± 5%	**Plating**	Sn 100%	(Pb Free)
			⑨ **Product**	Normal	
⑥	**Rated Voltage**	630 V	⑩ **Special**	Reserved for future use	
⑦	**Thickness**	1.60 ± 0.20 mm	⑪ **Packaging**	Embossed Type, 7" reel	

B. Structure and dimension



Samsung P/N	Dimension(㎜)			
	L	W	T	BW
CL31C102JHHNNNE	3.20 ± 0.20	1.60 ± 0.20	1.60 ± 0.20	0.50 ± 0.30

C. Samsung Reliability Test and Judgement condition

	Performance	Test condition
Capacitance	Within specified tolerance	1㎒±10% / 0.5~5Vrms
Q	1,000 min	
Insulation Resistance	10,000Mohm or 500Mohm×㎌ Whichever is smaller	500 ±50 Vdc 60±5 sec.
Appearance	No abnormal exterior appearance	Microscop (X10)
Withstanding Voltage	No dielectric breakdown or mechanical breakdown	150% of the rated voltage
Temperature Characteristics	C0G (From -55℃ to 125℃, Capacitance change should be within ±30PPM/℃)	
Adhesive Strength of Termination	No peeling shall be occur on the terminal electrode	500g×F, for 10±1 sec.
Bending Strength	Capacitance change : within ±5% or ±0.5㎊ whichever is larger	Bending to the limit (1mm) with 1.0mm/sec.
Solderability	More than 75% of terminal surface is to be soldered newly	SnAg3.0Cu0.5 solder 245±5℃, 3±0.3sec. (preheating : 80~120℃ for 10~30sec.)
Resistance to Soldering heat	Capacitance change : within ±2.5% or ±0.25㎊ whichever is larger Tan δ, IR : initial spec.	Solder pot : 270±5℃, 10±1sec.
Vibration Test	Capacitance change : within ±2.5% or ±0.25㎊ whichever is larger Tan δ, IR : initial spec.	Amplitude : 1.5mm From 10㎐ to 55㎐ (return : 1min.) 2hours ´ 3 direction (x, y, z)
Moisture Resistance	Capacitance change : within ±7.5% or ±0.75㎊ whichever is larger Q : 200 min IR : 500Mohm or 25Mohm × ㎌ Whichever is smaller	With rated voltage 40±2℃, 90~95%RH, 500+12/-0hrs
High Temperature Resistance	Capacitance change : within ±3% or ±0.3㎊ whichever is larger Q : 350 min IR : 1,000Mohm or 50Mohm × ㎌ Whichever is smaller	With 120% of the rated voltage Max. operating temperature 1000+48/-0hrs
Temperature Cycling	Capacitance change : within ±2.5% or ±0.25㎊ whichever is larger Tan δ, IR : initial spec.	1 cycle condition Min. operating temperature → 25℃ → Max. operating temperature → 25℃ 5 cycle test

※ The reliability test condition can be replaced by the corresponding accelerated test condition.

D. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5℃, 10sec. Max)

⚠ Product specifications included in the specifications are effective as of March 1, 2013.
Please be advised that they are standard product specifications for reference only.
We may change, modify or discontinue the product specifications without notice at any time.
So, you need to approve the product specifications before placing an order.
Should you have any question regarding the product specifications,
please contact our sales personnel or application engineers.